

Andrew A Shapiro

List of Publications by Year in descending order

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49
papers

2,888
citations

361413

20
h-index

345221

36
g-index

49
all docs

49
docs citations

49
times ranked

2493
citing authors

#	ARTICLE	IF	CITATIONS
1	Functionally graded material of 304L stainless steel and inconel 625 fabricated by directed energy deposition: Characterization and thermodynamic modeling. <i>Acta Materialia</i> , 2016, 108, 46-54.	7.9	432
2	Additive manufacturing of a functionally graded material from Ti-6Al-4V to Invar: Experimental characterization and thermodynamic calculations. <i>Acta Materialia</i> , 2017, 127, 133-142.	7.9	298
3	Willingness to engage in a pro-environmental behavior: An analysis of e-waste recycling based on a national survey of U.S. households. <i>Resources, Conservation and Recycling</i> , 2012, 60, 49-63.	10.8	273
4	Household Willingness to Recycle Electronic Waste. <i>Environment and Behavior</i> , 2006, 38, 183-208.	4.7	227
5	Developing Gradient Metal Alloys through Radial Deposition Additive Manufacturing. <i>Scientific Reports</i> , 2014, 4, 5357.	3.3	222
6	The Electronics Revolution: From E-Wonderland to E-Wasteland. <i>Science</i> , 2009, 326, 670-671.	12.6	209
7	Development and characterization of Ti-6Al-4V to 304L stainless steel gradient components fabricated with laser deposition additive manufacturing. <i>Materials and Design</i> , 2016, 104, 404-413.	7.0	201
8	Advances in additive manufacturing of metal-based functionally graded materials. <i>International Materials Reviews</i> , 2021, 66, 1-29.	19.3	169
9	Additive Manufacturing for Aerospace Flight Applications. <i>Journal of Spacecraft and Rockets</i> , 2016, 53, 952-959.	1.9	105
10	Leaching Assessments of Hazardous Materials in Cellular Telephones. <i>Environmental Science & Technology</i> , 2007, 41, 2572-2578.	10.0	104
11	Characterization of a functionally graded material of Ti-6Al-4V to 304L stainless steel with an intermediate V section. <i>Journal of Alloys and Compounds</i> , 2018, 742, 1031-1036.	5.5	89
12	How much e-waste is there in US basements and attics? Results from a national survey. <i>Journal of Environmental Management</i> , 2009, 90, 3322-3331.	7.8	70
13	California households' willingness to pay for "green" electronics. <i>Journal of Environmental Planning and Management</i> , 2007, 50, 113-133.	4.5	65
14	Understanding Preferences for Recycling Electronic Waste in California. <i>Environment and Behavior</i> , 2009, 41, 101-124.	4.7	50
15	Thin and Thermally Stable Periodic Metastructures. <i>Experimental Mechanics</i> , 2013, 53, 1735-1742.	2.0	45
16	Adopting Lead-Free Electronics: Policy Differences and Knowledge Gaps. <i>Journal of Industrial Ecology</i> , 2004, 8, 59-85.	5.5	40
17	Cryogenic Charpy impact testing of metallic glass matrix composites. <i>Scripta Materialia</i> , 2012, 66, 284-287.	5.2	40
18	Cryogenic in situ microcompression testing of Sn. <i>Acta Materialia</i> , 2014, 78, 56-64.	7.9	38

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19	Design and Evaluation of Bioepoxy-Flax Composites for Printed Circuit Boards. IEEE Transactions on Electronics Packaging Manufacturing, 2008, 31, 211-220.	1.4	34
20	Analysis of formation and growth of the β phase in additively manufactured functionally graded materials. Journal of Alloys and Compounds, 2020, 814, 151729.	5.5	28
21	Experimental analysis and thermodynamic calculations of an additively manufactured functionally graded material of V to Invar 36. Journal of Materials Research, 2018, 33, 1642-1649.	2.6	20
22	Integration of Processing and Microstructure Models for Non-Equilibrium Solidification in Additive Manufacturing. Metals, 2021, 11, 570.	2.3	15
23	Stress testing of a recrystallizing CaO-B ₂ O ₃ -SiO ₂ glass-ceramic with Ag electrodes for high frequency electronic packaging. Journal of Electronic Materials, 2001, 30, 386-390.	2.2	13
24	Computational Evolutionary Embryogeny. IEEE Transactions on Evolutionary Computation, 2010, 14, 301-325.	10.0	13
25	Electronic Packaging Materials for Extreme, Low Temperature, Fatigue Environments. IEEE Transactions on Advanced Packaging, 2010, 33, 408-420.	1.6	13
26	A comparison of microstrip models to low temperature co-fired ceramic-silver microstrip measurements. Microelectronics Journal, 2002, 33, 443-447.	2.0	12
27	A study of solder alloy ductility for cryogenic applications. , 2013, , .		10
28	WIAD Minimization in Butterfly Laser Module Packages: Clip Design. IEEE Transactions on Advanced Packaging, 2007, 30, 499-505.	1.6	9
29	A Comparative Hierarchical Decision Framework on Toxics Use Reduction Effectiveness for Electronic and Electrical Industries. Environmental Science & Technology, 2007, 41, 373-379.	10.0	7
30	Transition to Lead-Free Products in the US Electronics Industry: A Model of Environmental, Technical, and Economic Preferences. Environmental Modeling and Assessment, 2011, 16, 107-118.	2.2	6
31	Electronic Waste Recycling Preferences in California: The Role of Environmental Attitudes and Behaviors. Electronics and the Environment, IEEE International Symposium on, 2007, , .	0.0	5
32	Chip-on-Board (CoB) technology for low temperature environments. Part I: Wire profile modeling in unencapsulated chips. Microelectronics Reliability, 2007, 47, 1246-1250.	1.7	5
33	Adaptive Fault Tolerance for Scalable Cluster Computing in Space. International Journal of High Performance Computing Applications, 2009, 23, 227-241.	3.7	5
34	Renewable-resource Printed Wiring Board Design using Natural Fibers and a Bio-based Thermosetting Matrix. Electronics and the Environment, IEEE International Symposium on, 2007, , .	0.0	3
35	Fabrication defects and limitations of AlSi10Mg lattice structures manufactured by selective laser melting. Proceedings of the Institution of Mechanical Engineers, Part L: Journal of Materials: Design and Applications, 2021, 235, 2071-2082.	1.1	3
36	Reliability of semiconductor laser packaging in space applications. , 2008, , .		2

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37	Integrating toxicity reduction strategies for materials and components into product design: A case study on utility meters. <i>Integrated Environmental Assessment and Management</i> , 2013, 9, 319-328.	2.9	2
38	Semiconductor lasers beyond the fiber optics telecommunication wavelength. , 2005, , .		1
39	Introspection-Based Fault Tolerance for COTS-Based High-Capability Computation in Space. , 2008, , .		1
40	Moisture absorption phenomena in green composite printed circuit board prototypes. , 2008, , .		1
41	Genetic Programming of an Artificial Neural Network for Robust Control of a 2-D Path Following Robot. , 2008, , .		1
42	Engineering by Fundamental Elements of Evolution. , 2008, , .		1
43	In-Situ SEM Characterization of Fracture Behavior. <i>Microscopy and Microanalysis</i> , 2012, 18, 792-793.	0.4	1
44	A Fast Technology Infusion Model for Aerospace Organizations. , 2007, , .		0
45	Promoting Robust Design of Diode Lasers for Space: A National Initiative. <i>Aerospace Conference Proceedings IEEE</i> , 2008, , .	0.0	0
46	A novel energy-based approach for merging finite elements. <i>International Journal for Numerical Methods in Engineering</i> , 2011, 85, 187-205.	2.8	0
47	Toxicity potential indicator analysis for alternatives recommendations in the RIO Tronics utility meter pulse products. , 2011, , .		0
48	Genetic Evolution for the Development of Robust Artificial Neural Network Logic Gates. , 2009, , .		0
49	Technology Management. , 2014, , 599-618.		0